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INTERNATIONAL STANDARD

NORME INTERNATIONALE

colour inside

Metallic communication cable test methods – Part 4-10: Electromagnetic compatibility (EMC) – Transfer impedance and screening attenuation of feed-throughs and electromagnetic gaskets – Double coaxial test method

Méthodes d'essai des câbles métalliques de communication – Partie 4-10: Compatibilité électromagnétique (CEM) – Impédance de transfert et affaiblissement d'écran des traversées et des joints d'étanchéité électromagnétiques – Méthode d'essai coaxiale double

IEC 62153-4-10:2015-11+AMD1:2020-07 CSV(en-fr)

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FOREWORD

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IEC 62153-4-10 edition 2.1 contains the second edition (2015-11) [documents 46/563/FDIS and 46/580/RVD] and its amendment 1 (2020-07) [documents 46/736/CDV and 46/769/RVC].

In this Redline version, a vertical line in the margin shows where the technical content is modified by amendment 1. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.

International Standard IEC 62153-4-10 has been prepared by IEC technical committee 46: Cables, wires, waveguides, R.F. connectors, R.F. and microwave passive components and accessories.

This second edition constitutes a technical revision.

The main technical changes with regard to the previous edition are as follows:

– addition of a new clause that describes a procedure for verification of the measurement set-up and further information regarding sample preparation;
– addition of a new Annex that describes how to improve measurement certainty in the very low frequency area.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 62153 series, under the general title: *Metallic communication cable test methods*, can be found on the IEC website.

The committee has decided that the contents of the base publication and its amendment will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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METALLIC COMMUNICATION CABLE TEST METHODS –

Part 4-10: Electromagnetic compatibility (EMC) – Transfer impedance and screening attenuation of feed-throughs and electromagnetic gaskets – Double coaxial test method

1 Scope

This part of IEC 62153 details a coaxial method suitable for determining the transfer impedance and/or screening attenuation of feed-throughs and electromagnetic gaskets.

The shielded screening attenuation test set-up according to IEC 62153-4-4 (triaxial method) has been modified to take into account the particularities of feed-throughs and gaskets.

A wide dynamic and frequency range can be applied to test even super screened feed-throughs and gaskets with normal instrumentation from low frequencies up to the limit of defined transversal waves in the coaxial circuits at approximately 4 GHz.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

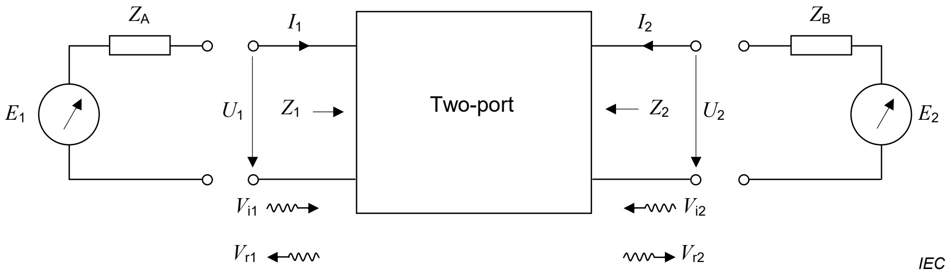
Void.

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

3.1
operational (Betriebs) transfer function in the forward direction H_{B21}
operational (Betriebs) scattering parameter S_{21}
quotient of the reflected square root of power wave fed into the reference impedance of the output of the two-port and the unreflected square root of the power wave consumed at the input of the two-port

EXAMPLE (see Figure 1)



Key

E_1, E_2	network analyzer at input, output respectively	V_{i1}, V_{i2}	incident square root of complex power waves (see note) at input and output, respectively
Z_A, Z_B	reference impedance at input and output respectively	V_{r1}, V_{r2}	reflected square root of complex power waves (see note) at input and output, respectively
I_1, I_2	current at input and output, respectively	Z_1, Z_2	impedance at input and output, respectively
U_1, U_2	voltage at input and output, respectively		

Figure 1 – A two-port

Note 1 to entry: Complex power is the product $U \cdot I$. Apparent power is the product $U \cdot I^*$, which is used in electrical power technique, where the angle between the voltage and current is of interest. I^* Is the complex conjugate of the current I.

S_{21} or H_{B21} is the operational (Betriebs) transfer function in the forward direction defined as follows:

$$S_{21} = \left.\frac{V_{r2}}{V_{i1}}\right|_{V_{i2}=0} = \frac{2U_2}{E_1}\sqrt{\frac{Z_A}{Z_B}} = H_{B21}$$

See Annex C of IEC TR 62152:2009.

3.2
transfer impedance
equivalent circuit of the measurement of a feed-through or gasket, shunt impedance Z_T between the primary and secondary circuit

EXAMPLE The transfer impedance of an electrically short screen is defined as the quotient of the open circuit voltage U_2 induced to the secondary circuit by the current I_1 fed into the primary circuit or vice versa. See Figure 2.

Z_T of an electrically short screen is expressed in Ω or decibels in relation to 1 Ω.

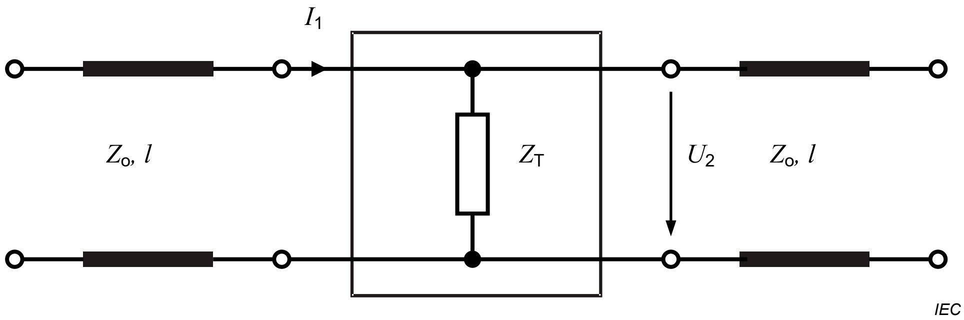


Figure 2 – Equivalent circuit of the test set-up and definition of Z_T

$$Z_T = \frac{U_2}{I_1} \quad (1)$$

$$Z_{\mathrm{T}} = +20 \times \log_{10}\left(\frac{|Z_{\mathrm{T}}|}{1\Omega}\right) \tag{2}$$

3.3
operational (Betriebs) attenuation
the quotient of the unreflected square root of power wave fed into the reference impedance of the input of the two-port and the square root of the power wave consumed by the load of the two-port expressed in dB and radians

Note 1 to entry: See IEC TR 62152.

3.4
screening attenuation
a_{s}
logarithmic ratio of the incident (unreflected) square root of power wave fed into the nominal impedance of the primary circuit of the test set-up and the periodic maximum values of the square root of power wave $V_{\mathrm{r2,\,max}}$ coupled into the secondary circuit of the test set-up when its characteristic impedance Z_{o} is normalized to 150 Ω

EXAMPLE

$$\begin{aligned} a_{\mathrm{s}} &= -20 \times \log_{10}\left(\mathrm{Env}\left|\frac{V_{\mathrm{r2,max}}}{V_{\mathrm{i1}}}\right|\right) + 20 \times \log_{10}\left|\frac{\sqrt{150\ \Omega}}{\sqrt{Z_{\mathrm{o}}}}\right| = \\ &= 20 \times \log_{10}\left|\frac{1}{\mathrm{Env}(S_{21,\max})}\right| + 20 \times \log_{10}\left|\frac{\sqrt{150\ \Omega}}{\sqrt{Z_{\mathrm{o}}}}\right| = \\ &= \text{Min. Env } (A_{\mathrm{B21}}) + 20 \times \log_{10}\left|\frac{\sqrt{150\ \Omega}}{\sqrt{Z_{\mathrm{o}}}}\right| \end{aligned} \tag{3}$$

where

a_{s}	is the screening attenuation expressed in dB;
Env (A_{B21})	is the operational attenuation recorded as the envelope curve of the measured values in dB (See 7.1);
Min.Env (A_{B21})	is the operational attenuation recorded as the minimum envelope curve of the measured values in dB (See 7.1);
150 Ω	is the standardized impedance of the secondary (“outer” or disturbed) circuit.

The screening attenuation, expressed in dB of an electrically short device is:

$$a_{\mathrm{s}} \approx 20 \times \log_{10}\left|\frac{50\Omega}{Z_{\mathrm{T}}}\right| \tag{4}$$

where

a_{s}	is the screening attenuation expressed in Ω;
Z_{T}	is the transfer impedance of the device under test.

Note 1 to entry: Formula (4) may be deduced from Formulas (3) and (5) as follows, assuming an electrically short device:

$a_{\mathrm{s}} = 20 \times \log_{10}\left|\frac{\sqrt{Z_o \times 150\Omega}}{2 \times Z_{\mathrm{T}}}\right|$. If we assume that $150\ \Omega \approx 3 \times Z_{\mathrm{o}}$, then

$a_{\mathrm{s}} = 20 \times \log_{10}\left|\frac{150\Omega}{2\sqrt{3} \times Z_{\mathrm{T}}}\right|$ and approximate $2\sqrt{3} \approx 3$ then $a_{\mathrm{s}} \approx 20 \times \log_{10}\left|\frac{50\Omega}{Z_{\mathrm{T}}}\right|$ and Formula (4) is valid.

In the measurement, both primary and secondary circuits are low impedance. This leads to a 6 dB lower A_{B21} than in e.g. the tube measurement of connectors; see IEC 62153-4-7.

3.5
device under test
DUT
connector's body or screen, intended to be mounted to a shielding or screening wall (or box), or an electromagnetic gasket

3.6
triaxial test method
method for measuring the transfer impedance and screening attenuation of passive transmission components like cables and connectors in an triaxial arrangement

Note 1 to entry: Primarily used for components with elongated dimensions and therefore distributed coupling over the transfer impedance along the components.

See also IEC TS 62153-4-1.

3.7
double coaxial test method
method for measuring the transfer impedance and screening attenuation of passive transmission components like connector feed-throughs and electro magnetical gaskets in an cascaded arrangement

Note 1 to entry: Primarily used for short components with concentrated transfer impedance.

See also IEC TS 62153-4-1.

4 Principle of the test method

Figure 3 shows a typical feed-through construction where a coaxial connection is brought into a screened housing to a printed circuit board. Important are the coaxial connector body's and electromagnetic gasket's reliable connection to the screening or shielding box.

The electromagnetic tightness of a connector body's mounting or a gasket is measured as transfer impedance and/or screening attenuation.

The test set-up consists of two RF-tight coaxial systems separated by a metallic wall to which the DUT is mounted. The feed-through test set-up is shown in Figure 4. The gasket test set-up is shown in Figure 5. Here the gasket is pressed between two metallic plates.

The nominal impedances of both sides of the coaxial fixture should be the same as that of the test equipment. The generator side is called the primary circuit or inner circuit and the receiver side is called the secondary circuit or outer circuit.

The set-up is the same for measuring the transfer impedance and the screening attenuation.

Annex A gives a theoretical model of the test set-up. Useful information concerning the triaxial measurement technique is given in [3][1].

1 Figures in square brackets refer to the Bibliography.

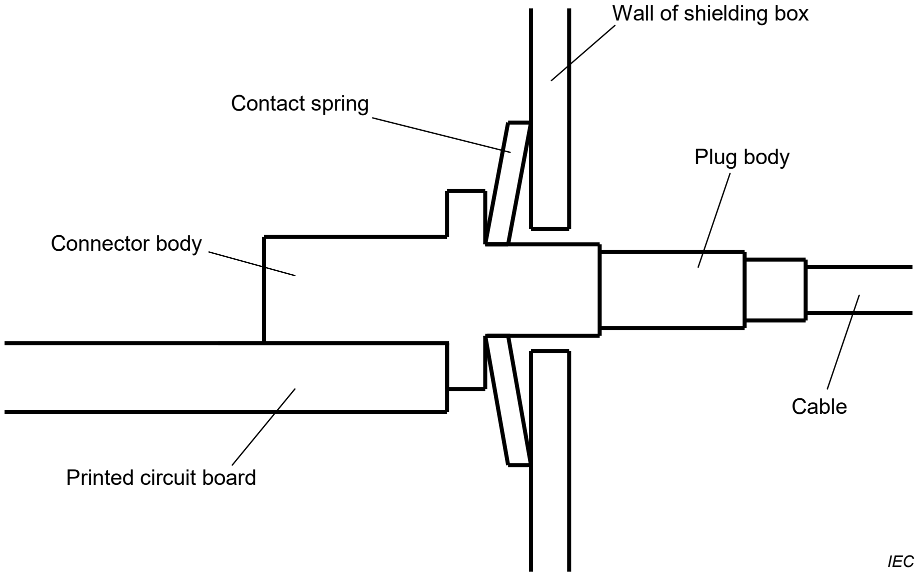
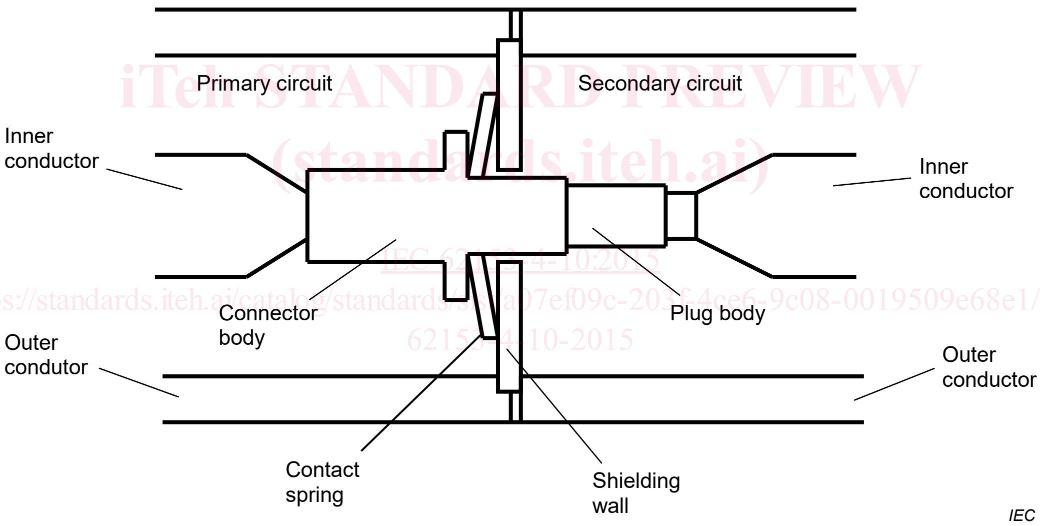
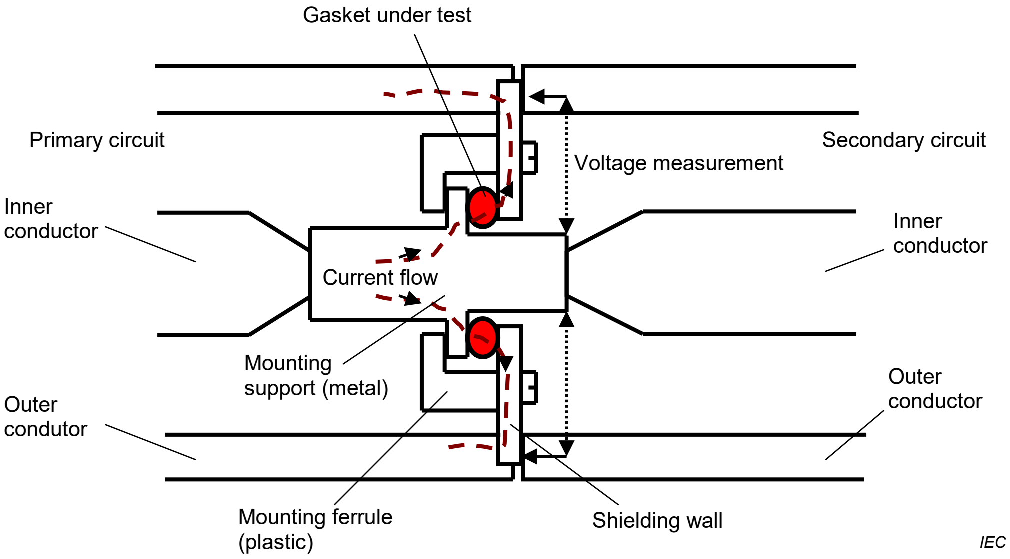


Figure 3 – Cross-section of a typical feed-through configuration



NOTE It is important that the coupled voltage is measured without any disturbing extra coupling voltage not coming from the feed-through under test (compare with Figure 5).

Figure 4 – Cross-section of the test fixture with a connector



In test rig design, care shall be taken that the disturbing current in the primary circuit cannot cause unwanted transition voltages in the measuring secondary circuit. Separate voltage and current "contacts" are a must.

One should not end in a situation where transition or contact resistances of the test rig influence the test results. Special care shall be taken to design the mounting of the test plate between the primary and secondary circuits or systems. Figure 5 shows how to avoid bringing the transition resistance between the mounting plate and primary circuit into the disturbing voltage measurement circuit formed by the secondary circuit of the test system.

It is important that the coupled voltage is measured without any disturbing extra coupling voltage not coming from the gasket under test (compare with Figure 4).

Figure 5 – Cross-section of the test fixture with an electromagnetic gasket